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** CONTINUING DATA ***** *None*** FOREIGN APPLICATIONS ***** *None*

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Foreign Priority claimed 35 USC 119 (a-d) conditions met	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance	STATE OR COUNTRY SINGAPORE	SHEETS DRAWING 1	TOTAL CLAIMS 9	INDEPENDENT CLAIMS 2
Verified and Acknowledged Examiner's Signature <i>Jan H. Hirsch</i>	Initials <i>THH</i>				

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TITLE

Mold FOR ENCAPSULATING A SEMICONDUCTOR CHIP

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